DISCRETE SEMICONDUCTORS

DATA SHEET

PDTA123E series PNP resistor-equipped transistors; R1 = 2.2 k Ω , R2 = 2.2 k Ω

Product specification Supersedes data of 2004 Apr 07 2004 Aug 02





PDTA123E series

FEATURES

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- · Reduced pick and place costs.

APPLICATIONS

- General purpose switching and amplification
- · Inverter and interface circuits
- Circuit driver.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	_	-50	V
Io	output current (DC)	-	-100	mA
R1	bias resistor	2.2	_	kΩ
R2	bias resistor	2.2	_	kΩ

DESCRIPTION

PNP resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

PRODUCT OVERVIEW

TYPE NUMBER	PACE	(AGE	MARKING CODE	NPN COMPLEMENT	
	PHILIPS	EIAJ	WARKING CODE	NPN COMPLEMENT	
PDTA123EE	SOT416	SC-75	5C	PDTC123EE	
PDTA123EEF	SOT490	SC-89	6C	PDTC123EEF	
PDTA123EK	SOT346	SC-59	42	PDTC123EK	
PDTA123EM	SOT883	SC-101	F7	PDTC123EM	
PDTA123ES	SOT54 (TO-92)	SC-43	TA123E	PDTC123ES	
PDTA123ET	SOT23	-	*21 ⁽¹⁾	PDTC123ET	
PDTA123EU	SOT323	SC-70	*42 ⁽¹⁾	PDTC123EU	

Note

^{1.} * = p: Made in Hong Kong.

^{* =} t: Made in Malaysia.

^{* =} W: Made in China.

PNP resistor-equipped transistors; R1 = 2.2 k Ω , R2 = 2.2 k Ω

PDTA123E series

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL		PINNING		
I TPE NUMBER	SIMPLIFIED OUTLINE AND STMBOL	PIN	DESCRIPTION		
PDTA123ES	## R1	1 2 3	base collector emitter		
PDTA123EE PDTA123EEF PDTA123EK PDTA123ET PDTA123EU	3 1 R2 2 Top view MDB271	1 2 3	base emitter collector		
PDTA123EM	2 R1 3 Bottom view MDB267	1 2 3	base emitter collector		

PNP resistor-equipped transistors; R1 = 2.2 k Ω , R2 = 2.2 k Ω

PDTA123E series

ORDERING INFORMATION

TYPE NUMBER	PACKAGE				
I TPE NUMBER	NAME	DESCRIPTION	VERSION		
PDTA123EE	_	plastic surface mounted package; 3 leads	SOT416		
PDTA123EEF	_	plastic surface mounted package; 3 leads	SOT490		
PDTA123EK	_	plastic surface mounted package; 3 leads	SOT346		
PDTA123EM	-	leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm	SOT883		
PDTA123ES	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54		
PDTA123ET	_	plastic surface mounted package; 3 leads	SOT23		
PDTA123EU	_	plastic surface mounted package; 3 leads	SOT323		

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-50	V
V _{CEO}	collector-emitter voltage	open base	_	-50	V
V _{EBO}	emitter-base voltage	open collector	_	-10	V
VI	input voltage				
	positive		_	+10	V
	negative		_	-12	V
Io	output current (DC)		_	-100	mA
I _{CM}	peak collector current		_	-100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT54	note 1	_	500	mW
	SOT23	note 1	_	250	mW
	SOT346	note 1	_	250	mW
	SOT323	note 1	_	200	mW
	SOT416	note 1	_	150	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

PNP resistor-equipped transistors; R1 = 2.2 k Ω , R2 = 2.2 k Ω

PDTA123E series

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	T _{amb} ≤ 25 °C		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT416	note 1	830	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0 \text{ A}$	_	_	-100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_{B} = 0 \text{ A}$	_	_	-1	μΑ
		$V_{CE} = -30 \text{ V}; I_{B} = 0 \text{ A}; T_{j} = 150 ^{\circ}\text{C}$	_	_	-50	μΑ
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_{C} = 0 \text{ A}$	_	_	-2	mA
h _{FE}	DC current gain	$V_{CE} = -5 \text{ V}; I_{C} = -20 \text{ mA}$	30	_	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	_	_	-150	mV
V _{i(off)}	input-off voltage	$I_C = -1 \text{ mA}; V_{CE} = -5 \text{ V}$	_	-1.2	-0.5	V
$V_{i(on)}$	input-on voltage	$I_C = -20 \text{ mA}; V_{CE} = -0.3 \text{ V}$	-2	-1.6	_	V
R1	input resistor		1.54	2.2	2.86	kΩ
R2 R1	resistor ratio		0.8	1	1.2	
C _c	collector capacitance	$I_E = I_e = 0 \text{ A}; V_{CB} = -10 \text{ V};$ f = 1 MHz	_	_	3	pF

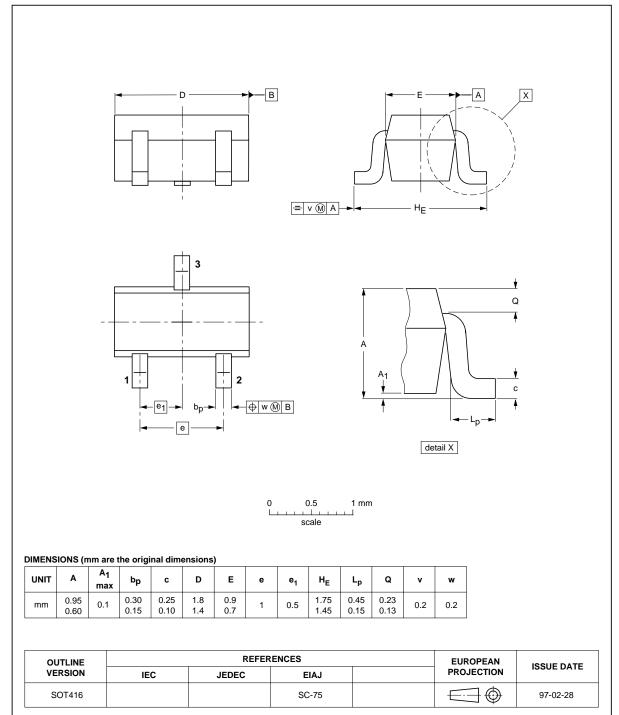
PNP resistor-equipped transistors; R1 = 2.2 k Ω , R2 = 2.2 k Ω

PDTA123E series

PACKAGE OUTLINES

Plastic surface mounted package; 3 leads

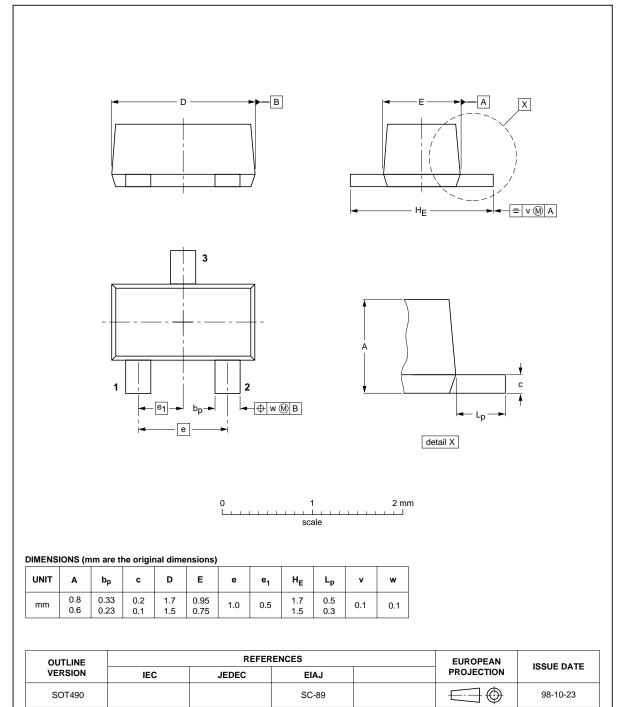
SOT416



PDTA123E series

Plastic surface mounted package; 3 leads

SOT490

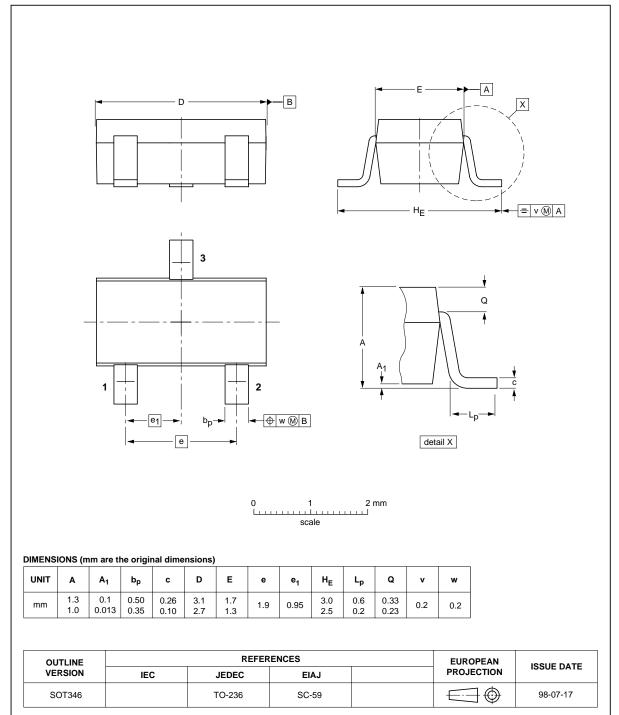


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PDTA123E series

Plastic surface mounted package; 3 leads

SOT346



PNP resistor-equipped transistors; $R1 = 2.2 \text{ k}\Omega, R2 = 2.2 \text{ k}\Omega$

PDTA123E series

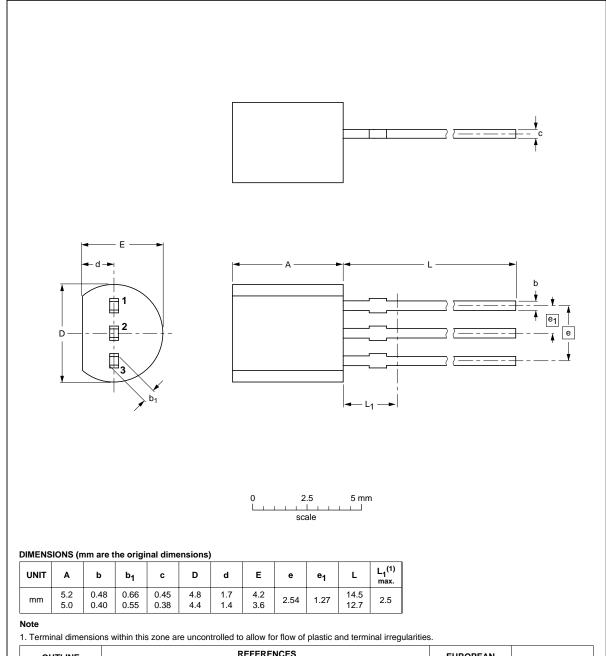
03-04-03

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm **SOT883** e₁ 1 mm **DIMENSIONS (mm are the original dimensions)** A₁ max. A⁽¹⁾ e₁ UNIT Ε L_1 0.55 0.30 0.50 0.20 0.62 1.02 0.30 0.03 0.35 0.65 mm 0.46 0.12 0.47 0.55 0.95 0.22 1. Including plating thickness OUTLINE VERSION REFERENCES EUROPEAN PROJECTION ISSUE DATE IEC **JEDEC JEITA** 03-02-05 SOT883 SC-101

PDTA123E series

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



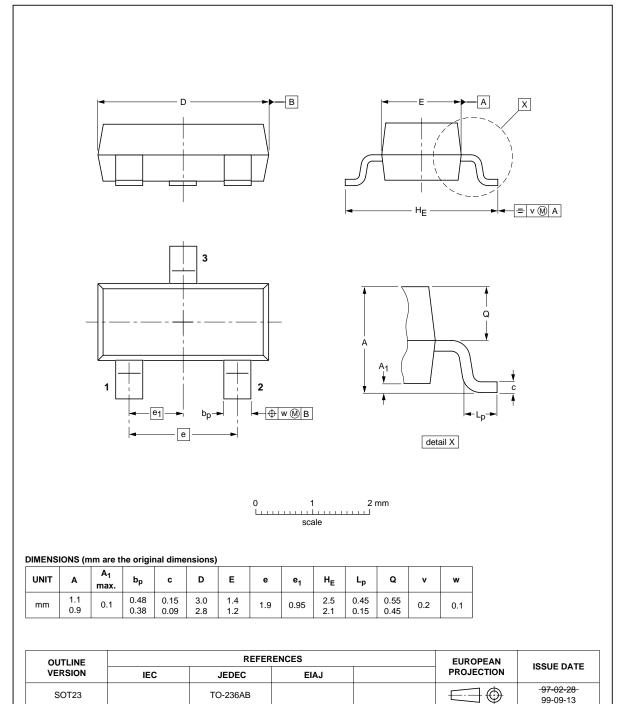
OUTLINE		REFERENCES			EUROPEAN	ISSUE DATE	
	VERSION	IEC	JEDEC	JEITA		PROJECTION	1330E DATE
	SOT54		TO-92	SC-43A			97-02-28 04-06-28

2004 Aug 02

PDTA123E series

Plastic surface mounted package; 3 leads

SOT23

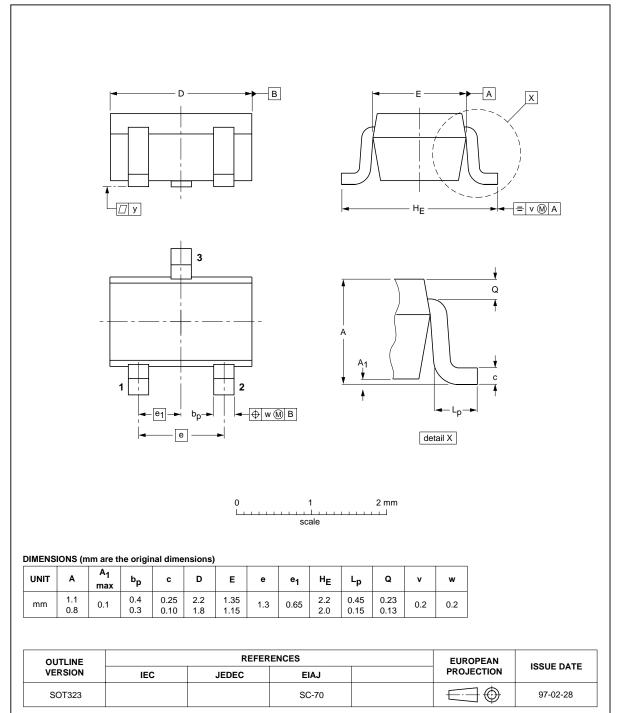


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PDTA123E series

Plastic surface mounted package; 3 leads

SOT323



PNP resistor-equipped transistors; R1 = $2.2 \text{ k}\Omega$, R2 = $2.2 \text{ k}\Omega$

PDTA123E series

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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